

STACKED CHIP PACKAGE WITH HEAT TRANSFER WIRES

ABSTRACT

The present invention provides a stacked chip package having at least one heat transfer wire. The heat transfer wire is disposed between the stacked chips and at least one end of each transfer wire is connected to a dummy pad provided on the board. Therefore, the heat generated by the chips and trapped between the chips can be effectively dissipated. The heat transfer wires can be formed on the uppermost chip of the stacked chips to enhance the heat dissipation. In addition, by controlling the number or the size of the heat transfer wire, the thermal characteristics of the stacked chip package can be modified.